

Supplier Name: Texas Instruments Inc. (DUNS# 00-732-1904)
 Contact Info: ti.com/support
 Form/Declaration Type: Distribute - RoHS and IEC 62474 DB
 Created on: 06/14/2022

Details for "LM358PWRG3"

Current Product Information

TI part number	Lead finish/Ball material	MSL rating/peak reflow	Assembly site	Package Pins	Package body size (mm)	Total device mass (mg)*
LM358PWRG3	SN	Level-1-260C-UNLIM	Ext-Mfg	PW 8	3x4.4x1.0	27.8

*Total Device Mass
 The summary mass is a rounded value and will be within approximately +/- 10% of the detailed mass value.

Environmental Ratings Information

RoHS	REACH	Green	IEC 62474 DB
Yes	Yes	Yes	Yes

Component Information

Component	Substance	CAS Number	Amount (mg)	Homogeneous Material Level		Component Level	
				Percentage %	ppm	Percentage %	ppm
Bond Wire							
Copper and Its Alloys	Copper	7440-50-8	0.035	97.588178	975882	0.125773	1258
Not Categorized	Proprietary Materials		0.000003	0.008365	84	0.000011	0
Precious Metals	Palladium	7440-05-3	0.000861	2.400669	24007	0.003094	31
Precious Metals	Silver	7440-22-4	0.000001	0.002788	28	0.000004	0
Sub-Total			0.035865	100	1000000	0.128881	1289
Die Attach Adhesive							
Precious Metals	Silver	7440-22-4	0.1365	81.999712	819997	0.490513	4905
Thermoplastics	Epoxy	85954-11-6	0.029964	18.000288	180003	0.107676	1077
Sub-Total			0.166464	100	1000000	0.598188	5982
Lead Frame							
Copper and Its Alloys	Copper	7440-50-8	5.679	94.65	946500	20.40749	204075
Magnesium and Its Alloys	Magnesium	7439-95-4	0.0105	0.175	1750	0.037732	377
Nickel and Its Alloys	Nickel	7440-02-0	0.192	3.2	32000	0.689952	6900
Other Inorganic Materials	Silicon	7440-21-3	0.0435	0.725	7250	0.156317	1563
Precious Metals	Silver	7440-22-4	0.075	1.25	12500	0.269513	2695
Sub-Total			6	100	1000000	21.561004	215610
Lead Frame Plating							
Other Nonferrous Metals and Alloys	Tin	7440-31-5	0.5	100	1000000	1.79675	17968
Sub-Total			0.5	100	1000000	1.79675	17968
Mold Compound							
Other Inorganic Materials	Fused Silica	60676-86-0	17.408488	84.850001	848500	62.557412	625574
Other Plastics and Rubber	Carbon Black	1333-86-4	0.030775	0.149999	1500	0.11059	1106
Thermoplastics	Epoxy	85954-11-6	3.077517	15	150000	11.059059	110591
Sub-Total			20.51678	100	1000000	73.727062	737271
Semiconductor Device							
Ceramics / Glass	Doped Silicon	7440-21-3	0.608909	100	1000000	2.188115	21881
Sub-Total			0.608909	100	1000000	2.188115	21881
Total			27.828018			100	1000000

Important Note
 The ppm calculations are at the **homogeneous material** level and are maximum concentration values. The ppm displayed represents the **homogeneous material** with the highest ppm for that substance. The amount (mg) calculations represent the maximum total amount of each substance within the component.
 The ppm calculations are at the **component** level and are average concentration values. The amount (mg) calculations represent the average total amount of each substance within the **component**.
[See Glossary of Terms for more details.](#)

Important Part Information
 There is a remote possibility the Customer Part Number (CPN) your company uses could reference more than one TI part number. This is due to two or more users (EMSI or subcontractors) using the same CPN for different TI part numbers. If this occurs, please check your Customer Part Number and cross reference it with the TI part number seen on this page.

Product Content Methodology
[For an explanation of the methods used to determine material weights, See Product Content Methodology.](#)

Material Declaration Certificate for Semiconductor IC Packaged Products

TI certifies that the material content information provided by TI is representative and accurate to the best of their knowledge based on material information provided by its suppliers and their combination into finished IC packaged products. TI semiconductor products designated to be "Pb-free", "Green" or "RoHS Exempt" fully meets the latest EU RoHS Directive requirements along with other legislation as seen in the former JIG-101 list that has been transferred to the IEC 62474 database.

Important Information/Disclaimer
 TI bases its material content information on information provided by third-party suppliers and has taken, and continues to take, reasonably diligent steps to provide any required or available information. TI may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers may consider certain information to be proprietary, and thus certain information may not be available for release by TI. The material content information is provided by TI "as is."
[For additional information, please contact TI customer support.](#)

[Signature: \(click here for a fuller statement with a signed certificate\)](#)

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 For further environmental statements, please go to www.ti.com/ecoinfo
 Created on: 06/14/2022

RoHS: Means TI semiconductor products that are compliant with the current RoHS requirement that the maximum concentration values of the ten substances listed in RoHS Annex II do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI semiconductor products labeled as "RoHS Compliant" are suitable for use in specified lead-free processes. TI may also reference these types of semiconductor products as "Pb-Free." These TI semiconductor products are also fully compliant with GADSL and the IEC 62474 database for electronic requirements.

RoHS Exempt: Means TI semiconductor products that contain lead (Pb) above the RoHS Annex II threshold, but that fall within one of the specific RoHS exemptions noted above or documented in <http://www.ti.com/lit/pdf/szzq088>

Green: Means the content of Chlorine (Cl) and Bromine (Br)-based flame retardants meet J57098 low halogen requirements of <=1 000ppm threshold; Antimony trioxide (Sb2O3) contained in halogen based flame retardant materials meets the <=1 000ppm threshold requirement; and Beryllium Oxide (BeO) is <=1000ppm.